NEW! Four Section Models

Reflectionless

Band Pass Filter Die

XBF-D-Series

50Ω 15.5 to 20.5 GHz

The Big Deal

- *High Stopband rejection, up to 77 dB*
- *Patented design terminates stopband signals*
- *Stop band up to 40 GHz*
- *Excellent repeatability through IPD* process*

Product Overview

Mini-Circuits' XBF-D-Series are GaAs MMIC reflectionless filters which includes 4-sections, giving you ultra-high rejection in the stopband – up to 77 dB! Reflectionless filters employ a patented filter topology which absorbs and terminates stopband signals internally rather than reflecting them back to the source. This new capability enables unique applications for filter circuits beyond those suited to traditional approaches. Traditional filters are reflective in the stopband, sending signals back to the source at 100% power.

These reflections interact with neighboring components and often result in intermodulation and other interferences. By eliminating stopband reflections, reflectionless filters can readily be paired with sensitive devices and used in applications that otherwise require circuits such as isolation amplifiers or attenuators.

Key Features	Advantages
Choice of BW 15.5 - 16.5 GHz 17.5 - 18.5 GHz 19.5 - 20.5 GHz	Three different models to cover the band XBF-163-D+ XBF-183-D+ XBF-24-D+
Easy integration with sensitive reflective components, e.g. mixers, multipliers	Reflectionless filters absorb unwanted signals, preventing reflections back to the source. This reduces generation of additional unwanted signals without the need for extra components like attenuators, improving system dynamic range and saving board space.
High stopband rejection, up to 77 dB	Ideal for applications where suppression of strong spurious signals and intermodulation products is needed.
Enables stable integration of wideband amplifiers	Because reflectionless filters maintain good impedance in the stop band; they can be integrated with high gain, wideband amplifiers without the risk of creating instabilities in these out of band regions.
Cascadable	Reflectionless filters can be cascaded in multiple sections to provide sharper and higher attenuation, while also preventing any standing waves that could affect pass band signals.
Excellent power handling in a tiny surface mount device up to 0.5W in passband	High power handling extends the usability of these filters to the transmit path for inter-stage filtering.
Unpackaged die	Enables the user to integrate the filter directly into hybrids
Excellent repeatability of RF performance	Through semiconductor IPD process, X-series filters are inherently repeatable for large volume production.
Operating temperature up to 105˚C	Suitable for operation close to high power components.

*IPD – Integrated Passive Device, is a GaAs semiconductor process

Reflectionless

Band Pass Filter Die

XBF-24-D+

50Ω 19.5 to 20.5 GHz

Features

- Match to 50Ω in the stop band, eliminates undesired reflections
- Cascadable
- Excellent stopband rejection, 51 dB typ.
- Temperature stable, up to 105°C
- Protected by US Patents 8,392,495; 9,705,467, additional patent pending
- Protected by China Patent 201080014266.1
- Protected by Taiwan Patent I581494

+RoHS Compliant

The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications

Ordering Information: Refer to Last Page

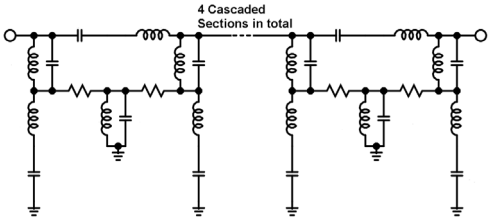
Applications

- Transmitters & Receivers
- Harmonic Rejection
- Spurious Rejection

General Description

Mini-Circuits' XBF-24-D+ four-section reflectionless filter Die employs a novel filter topology which absorbs and terminates stop band signals internally rather than reflecting them back to the source. This new capability enables unique applications for filter circuits beyond those suited to traditional approaches. Traditional filters are reflective in the stop band, sending signals back to the source at 100% of the power level. These reflections interact with neighboring components and often result in inter-modulation and other interferences. Reflectionless filters eliminate stop band reflections, allowing them to be paired with sensitive devices and used in applications that otherwise require circuits such as isolation amplifiers or attenuators.

Simplified Schematic and Pad description



Pad#	Description
2	RF-IN
5	RF-OUT
1,3,4,6	Ground
Die bottom	Ground

Note: 1. Bond Pad material - Gold
2. Bottom of Die - Gold plated

Bonding Pad Position

Dimensions in µm, Typical

L1	L2	L3	L4	L5	H1	H2	H3	H4	H5	Thickness	Bond pad size
80	2370	2470	2570	2650	80	550	650	750	1300	100	78 X 78

Electrical Specifications[1] at 25°C

Parameter		F#	Frequency (MHz)	Min.	Typ.	Max.	Unit
Pass Band	Insertion Loss	F2-F3	19500 - 20500		4.2		dB
	VSWR	F2-F3	19500 - 20500		1.8		:1
Stop Band, Lower	Rejection	DC-F1	DC - 10000		76		dB
	VSWR	DC-F1	DC - 10000		1.2		:1
Stop Band, Upper	Rejection	F4-F5	30000 - 32000		49		dB
		F5-F6	32000 - 40000		51		
	VSWR	F4-F5	30000 - 32000		1.5		:1
		F5-F6	32000 - 40000		1.2		

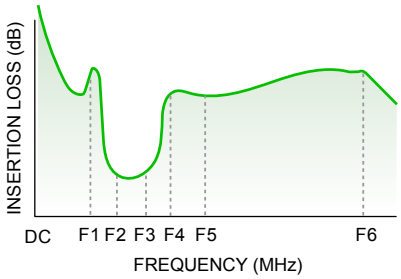
[1] Measured on die using MPI titan series 100µm pitch GSG probe.

Absolute Maximum Ratings[4]

Parameter	Ratings
Operating Temperature	-55°C to +105°C
RF Power Input, Passband (F2-F3)[2]	0.5W at 25°C
RF Power Input, Stopband (DC-F2, F3-F6)[3]	0.16W at 25°C

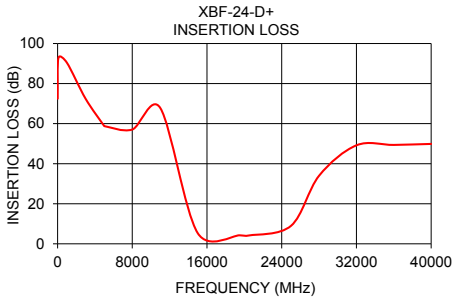
[2] Passband rating derates linearly to 0.25W at 105°C ambient
[3] Stopband rating derates linearly to 0.08W at 105°C ambient
[4] Permanent damage may occur if any of these limits are exceeded.

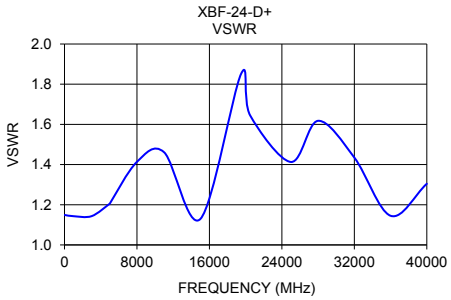
Specification Definition



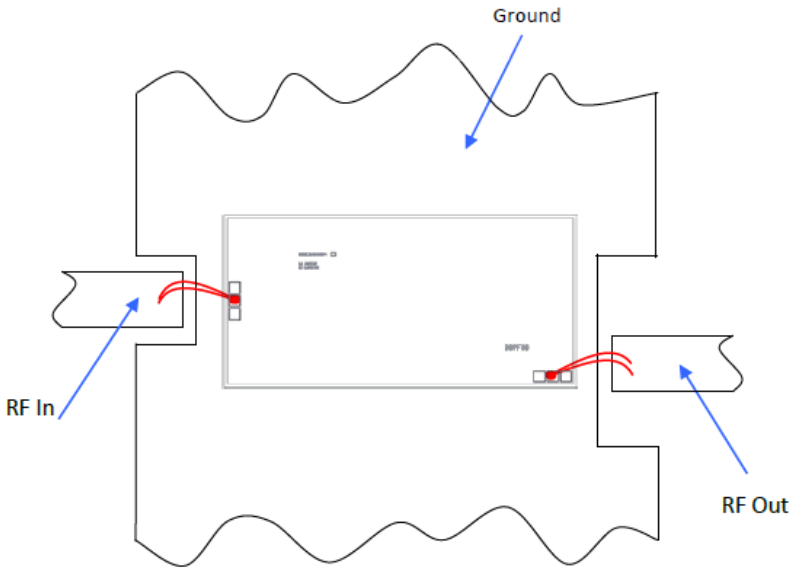
Typical Performance Data at 25°C

Frequency (MHz)	Insertion Loss (dB)	VSWR (:1)
10	72.43	1.15
100	92.92	1.15
500	86.26	1.15
1000	90.41	1.14
3000	72.43	1.14
5000	58.77	1.21
8000	57.05	1.41
11000	67.79	1.46
15000	5.39	1.13
19500	4.26	1.85
20500	4.19	1.64
25000	9.02	1.41
28000	34.01	1.62
32000	49.18	1.43
36000	49.37	1.15
40000	49.87	1.30





Assembly Diagram



Note: Ground bond wires are optional.

Assembly and Handling Procedure

1. Storage
   Dice should be stored in a dry nitrogen purged desiccators or equivalent.
2. ESD
   MMIC Gallium Arsenide (GaAs) filter dice are susceptible to electrostatic and mechanical damage. Die are supplied in antistatic protected material, which should be opened in clean room conditions at an appropriately grounded anti-static worksta tion. Devices need careful handling using correctly designed collets, vacuum pickup tips or sharp antistatic tweezers to deter ESD damage to dice.
3. Die Attach
   The Die mounting surface must be clean and flat. Using conductive silver filled epoxy, recommended epoxies are DieMat DM6030Hk-PT/H579/H579 or Ablestik 84-1LMISR4. Apply sufficient epoxy to meet required epoxy bond line thickness, epoxy fillet height and epoxy coverage around total Die periphery. Parts shall be cured in a nitrogen filled atmosphere per manufac turer's cure condition. It is recommended to use antistatic Die pick up tools only.
4. Wire Bonding
   Bond pad openings in the surface passivation above the bond pads are provided to allow wire bonding to the dice gold bond pads. Thermosonic bonding is used with minimized ultrasonic content. Bond force, time, ultrasonic power and temperature are all critical parameters. Suggested wire is pure gold, 1 mil diameter. Bonds must be made from the bond pads on the Die to the package or substrate. All bond wires should be kept as short as low as reasonable to minimize performance degradation due to undesirable series inductance.

Additional Detailed Technical Information *additional information is available on our dash board.*	
Performance Data	Data Table
	Swept Graphs
	S-Parameter (S2P Files) Data Set with and without port extension(.zip file)
Case Style	Die
Die Ordering and packaging information	Quantity, Package — Model No. Small, Gel - Pak: 5,10,50,100 KGD* — XBF-24-DG+ Medium†, Partial wafer: KGD*<605 — XBF-24-DP+ †*Available upon request contact sales representative* Refer to AN-60-067
Environmental Ratings	ENV-80

*Known Good Dice ("KGD") means that the dice are taken from PCM good wafer and visually inspected in question have been subjected to Mini-Circuits while this is not definitive, it does help to provide a higher degree of confidence that dice are capable of meeting typical RF electrical parameters specified by Mini-Circuits.

ESD Rating**

Human Body Model (HBM): Class 1C (Pass 1000V) in accordance with ANSI/ESD STM 5.1 - 2001

** Tested in industry standard MCLP 4x4mm, 24-lead package.

Additional Notes

A. Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.

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MMIC Reflectionless Band Pass Filter Die XBF-24-D+

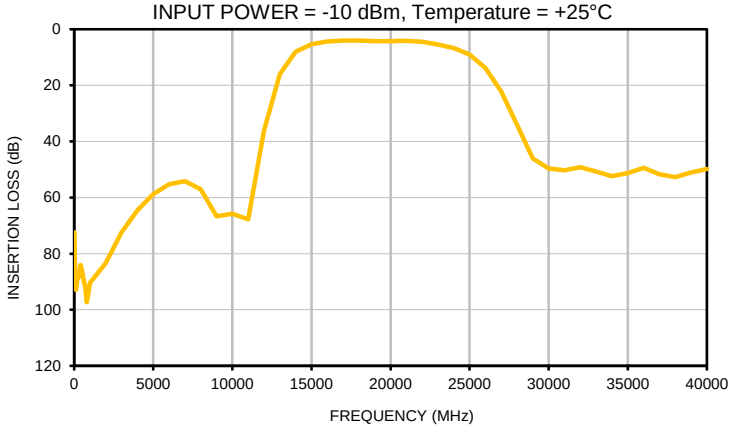
Typical Performance Data

Test Condition @ Temperature = +25°C

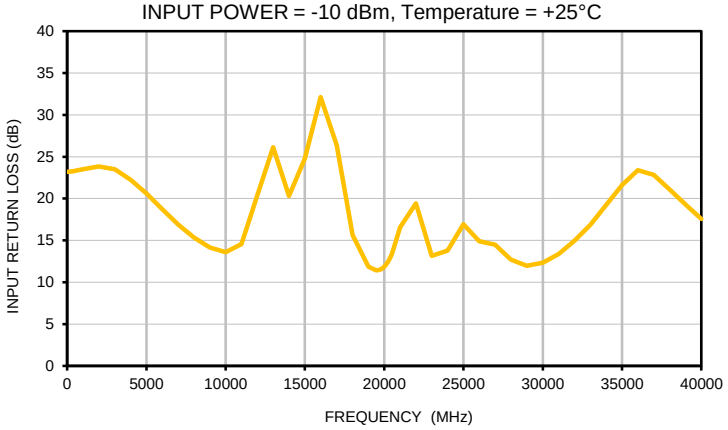
FREQ. (MHz)	INSERTION LOSS (dB)	INPUT RETURN LOSS (dB)	OUTPUT RETURN LOSS (dB)
10	72.43	23.20	24.92
50	83.99	23.19	24.91
100	92.92	23.20	24.94
200	88.63	23.23	24.97
300	88.40	23.25	25.01
400	84.01	23.28	25.05
500	86.26	23.32	25.09
600	89.44	23.34	25.13
700	91.97	23.38	25.18
800	97.29	23.43	25.23
900	94.35	23.46	25.28
1000	90.41	23.51	25.33
2000	83.35	23.83	25.44
3000	72.43	23.49	24.49
4000	64.60	22.22	22.66
5000	58.77	20.61	20.63
6000	55.22	18.71	18.67
7000	54.14	16.91	16.95
8000	57.05	15.32	15.63
9000	66.64	14.14	14.85
10000	65.75	13.60	14.93
11000	67.79	14.55	16.83
12000	36.17	20.40	20.71
13000	15.98	26.14	19.96
14000	8.05	20.29	18.17
15000	5.39	24.77	24.33
16000	4.40	32.12	27.94
17000	4.04	26.37	19.95
18000	4.05	15.64	13.85
19000	4.22	11.84	10.86
19500	4.26	11.42	10.49
19600	4.26	11.43	10.51
19700	4.26	11.46	10.56
19800	4.25	11.55	10.65
19900	4.24	11.69	10.78
20000	4.23	11.86	10.95
20100	4.23	12.07	11.14
20200	4.21	12.33	11.37
20300	4.20	12.63	11.63
20400	4.19	12.98	11.95
20500	4.19	13.41	12.27
21000	4.17	16.55	14.72
22000	4.51	19.41	16.70
23000	5.42	13.14	12.33
24000	6.65	13.80	12.86
25000	9.02	16.93	15.34
26000	13.81	14.91	14.15
27000	22.22	14.48	13.90
28000	34.01	12.69	12.54
29000	46.06	11.97	12.45
30000	49.60	12.33	13.52
31000	50.26	13.38	15.42
32000	49.18	14.96	18.14
33000	50.74	16.85	21.65
34000	52.37	19.22	25.76
35000	51.26	21.60	27.27
36000	49.37	23.39	24.74
37000	51.77	22.85	21.99
38000	52.67	21.10	20.01
39000	51.10	19.32	18.63
40000	49.87	17.58	17.60

Typical Performance Curves

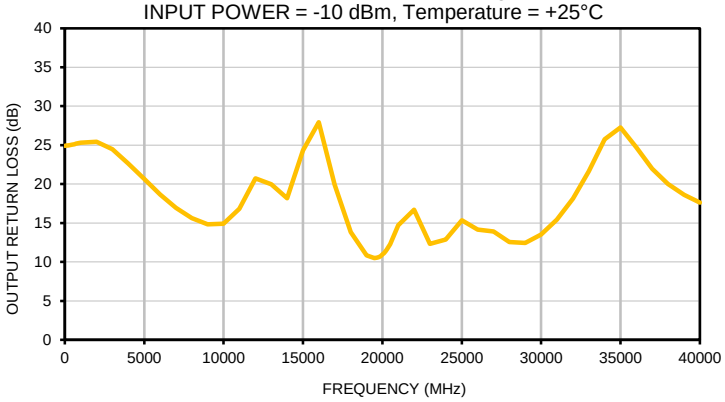
INSERTION LOSS vs. FREQUENCY
INPUT POWER = -10 dBm, Temperature = +25°C



INPUT RETURN LOSS vs. FREQUENCY
INPUT POWER = -10 dBm, Temperature = +25°C



OUTPUT RETURN LOSS vs. FREQUENCY
INPUT POWER = -10 dBm, Temperature = +25°C



Mini-Circuits

Environmental Specifications ENV80

All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-40° to 85° C or -40° to 105° C or -55° to 105° C or -45° to 105° C Ambient Environment	Refer to Individual Model Data Sheet
Storage Environment (Die)	-65° to 150°C	Individual Model Data Sheet
Storage Environment(Packaging)	-40° to 70°C and 40 to 60% humidity (In Factory Shipped Package)	

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